

SPECIFICATION

REFOND P/N

RF-A3E31-W60H-B3

R&D

Mass Production



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1. Description

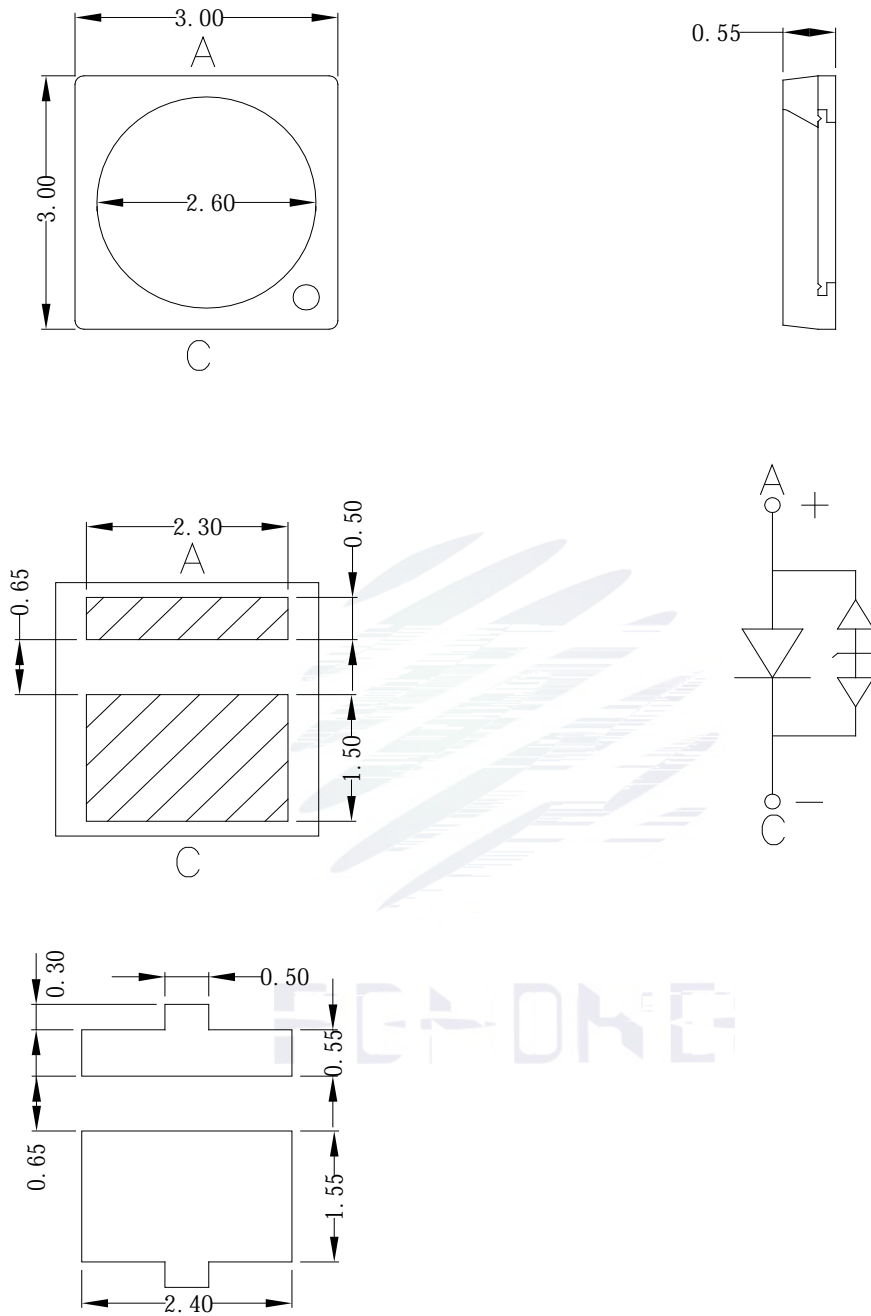
1.1

The White LED, which was fabricated by using a blue chip and the phosphor.

Product Package: 3.0mmX 0 CÜ0 I- 22 mØ R ° / Ì Ñ G = ° ž ò ¥nf6°D™ > *

REFOND

1.4 Package Dimension



Notes

All dimensions units are millimeters.

All dimensions tolerances are 0.2mm unless otherwise noted.



1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	$I_F=350\text{mA}$	2.8	3.1	3.4	V
Reverse Current	I_R	$V_R=5\text{V}$	---	---	---	μA
Luminous Flux	Φ	$I_F=350\text{mA}$	105	125	144	lm
Viewing Angle	2 θ 1/2	$I_F=350\text{mA}$	---	120	---	deg
Thermal Resistance.	R_{THJ-S}	$I_F=350\text{mA}$	---	---	14	$^{\circ}\text{C}/\text{W}$

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	P_D	1428	mW
Forward Current	I_F	420	mA
Peak Forward Current	I_{FP}	700	mA
Reverse Voltage	V_R	5	V
Electrostatic Discharge (HBM)	E_{SD}	8000	V
Operating Temperature	T_{OPR}	-40 ~ +125	
Storage Temperature	T_{STG}	-40 ~ +125	
Junction Temperature	T_J	150	



Notes

1. 1/10 Duty cycle, 10ms pulse width.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. $\pm 0.1V$.
3. The above color coordinates measurement allowance tolerance is ± 0.005 . \pm
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$. $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED
8. ESD yield is over 90% at 8000V ESD (HBM). ESD protection during products handling is needed. 90% LED
ESD OV ,

1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=350mA)

BIN (IF=350mA)

Table 1-3

V _F	G1	G2	H1	H2	I1	I2		
	2.8-2.9	2.9-3.0	3.0-3.1	3.1-3.2	3.2-3.3	3.3-3.4		
φ lm	SA	SB	TA					
	105-117	117-130	130-144					





1.7 Typical Optical Characteristics Curves

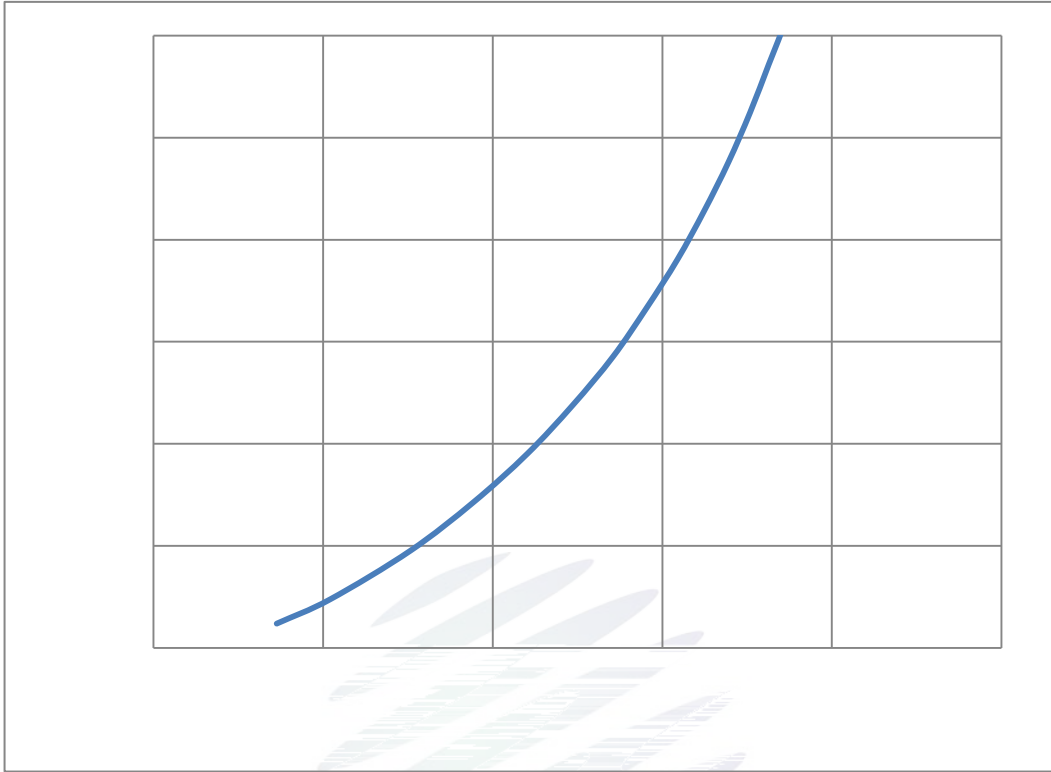


Fig. 1-7 Forward Voltage Vs Forward Current

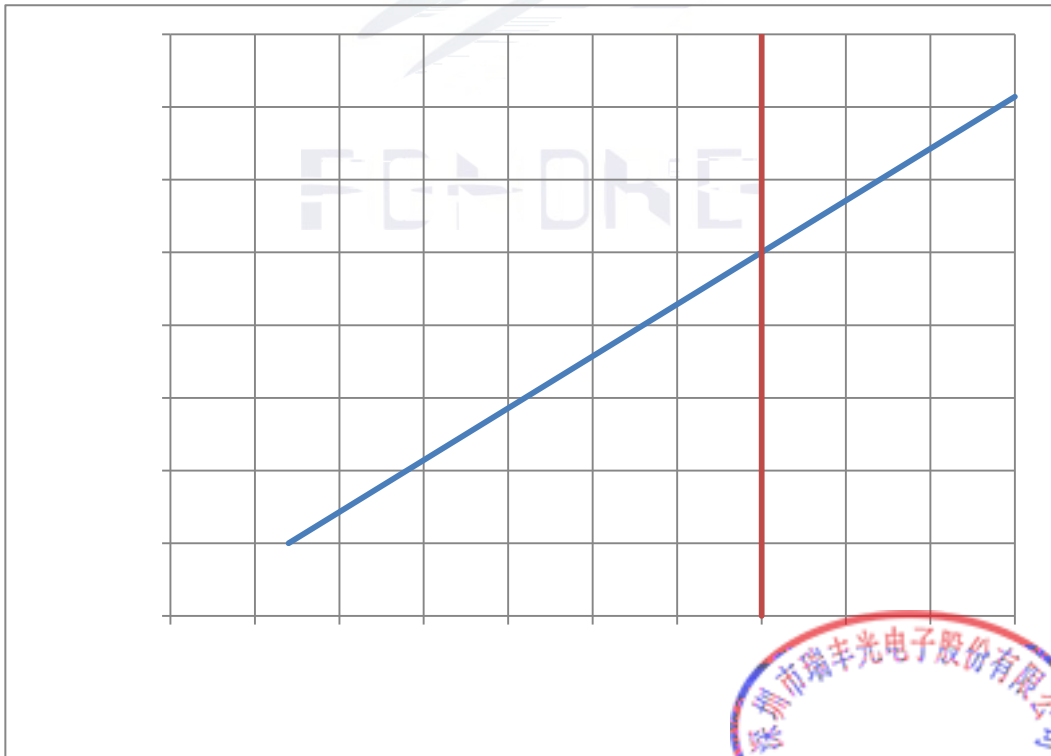


Fig. 1-8 Forward Current Vs Relative Intensity



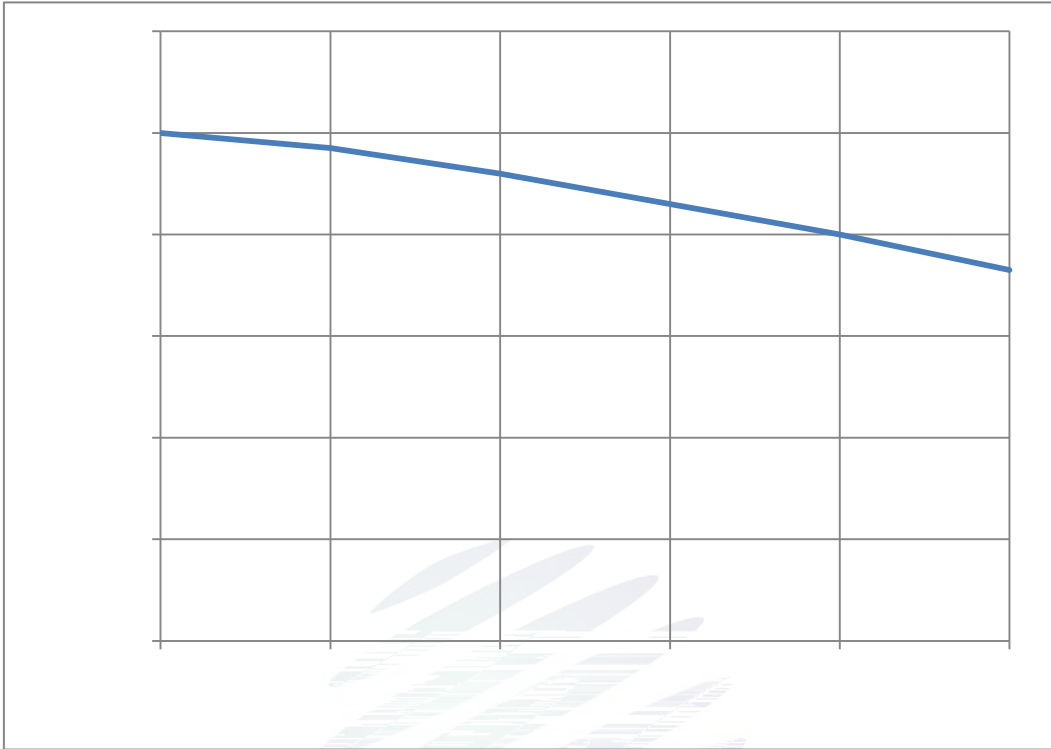
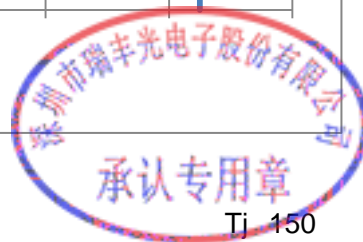


Fig. 1-9 Solder Temperature Vs Relative Intensity



Fig. 1-10 Solder Temperature Vs Forward Current



Ti 150

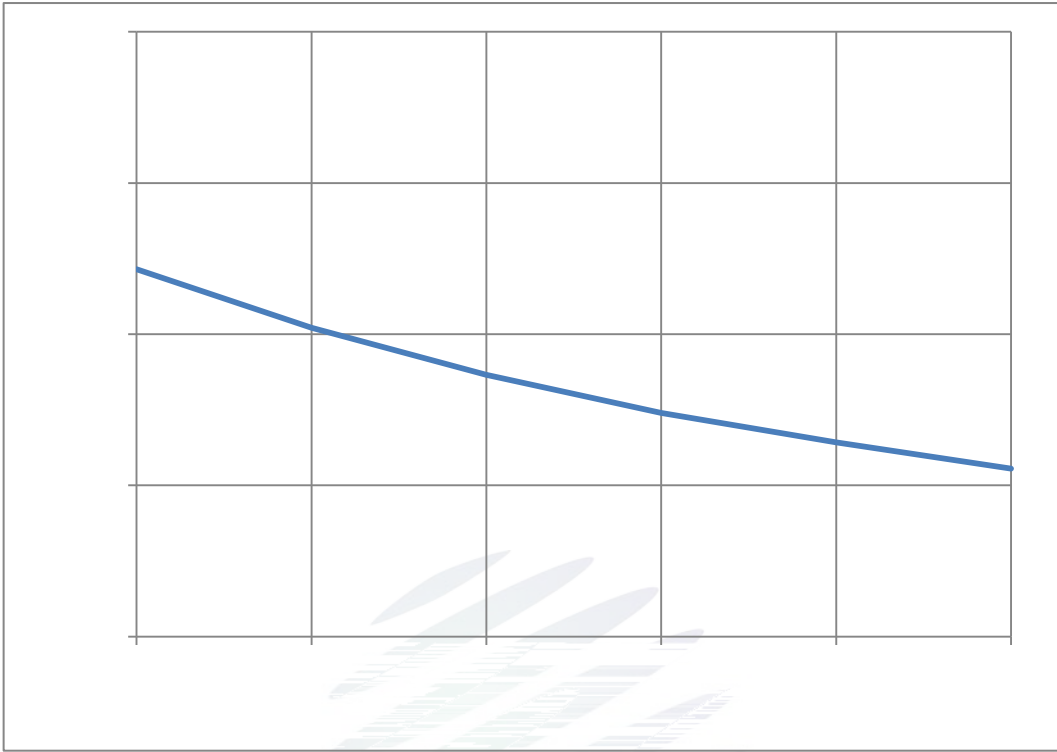


Fig. 1-11 Forward Voltage Vs Solder Temperature

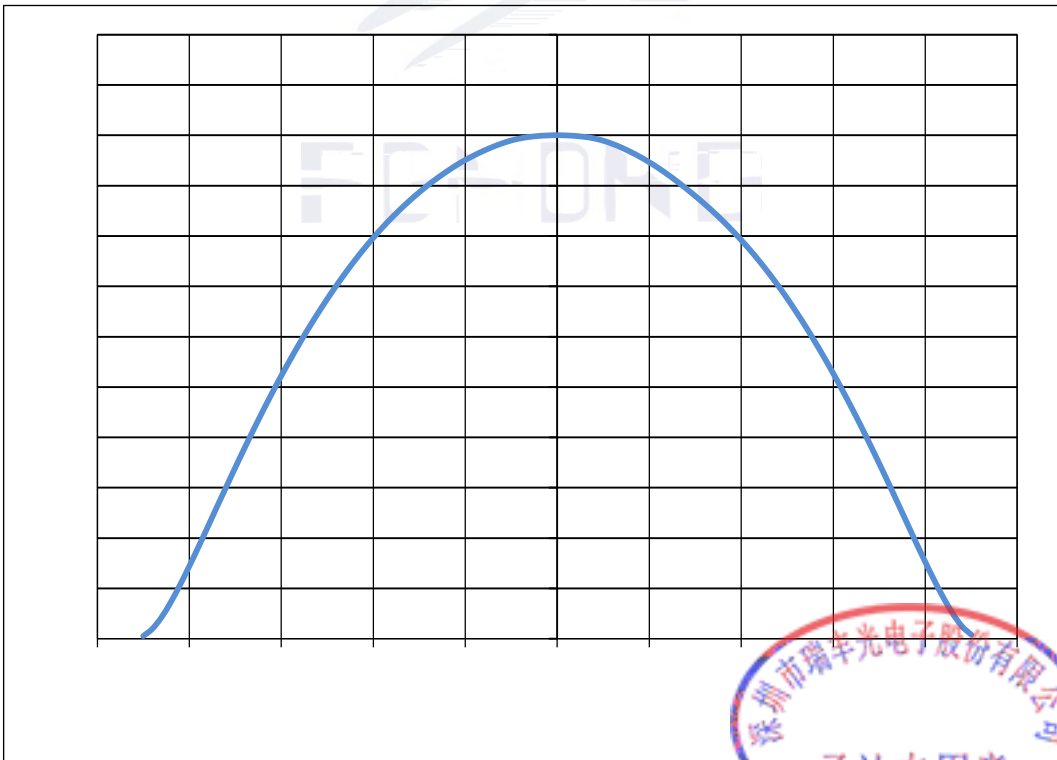


Fig. 1-12 Radiation diagram

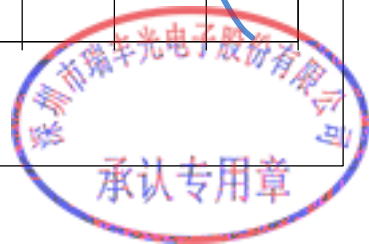


Fig. 1-13 Chromaticity Coordinate Vs Solder Temperature

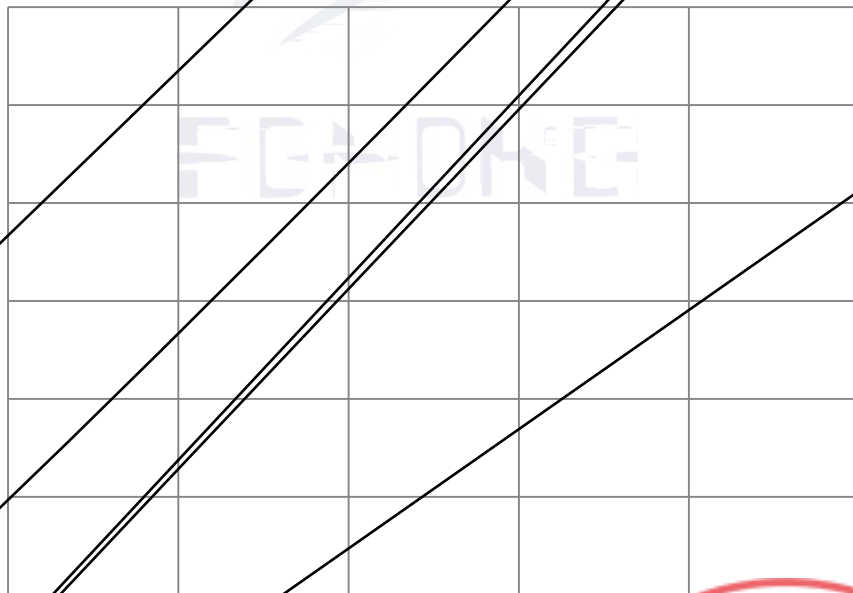
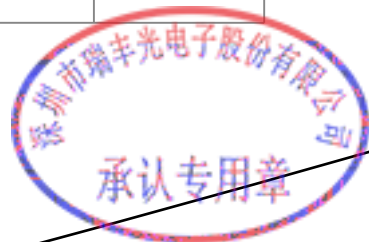


Fig. 1-14 Spectrum Distribution



2. Packaging

2.1 Packaging Specification

Package:4000pcs/reel.

2.1.1Carrier Tape Dimension

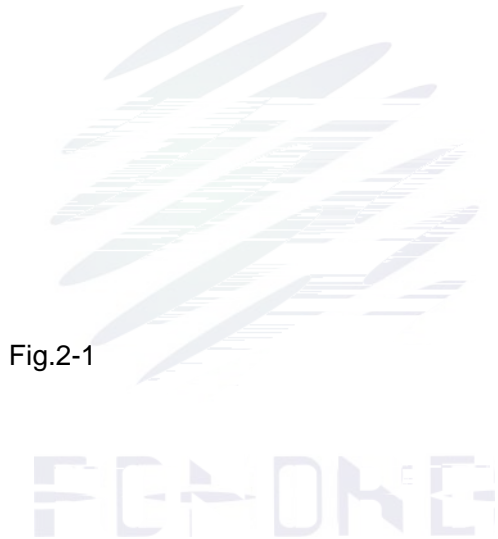


Fig.2-1

2.1.3 Label Form Specification

Table 2 Specification	
PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
Φ	Luminous flux
XY	Chromaticity Bin
V_F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

Fig. 2-3 Label Form Specification

2.2 Moisture Resistant Packing

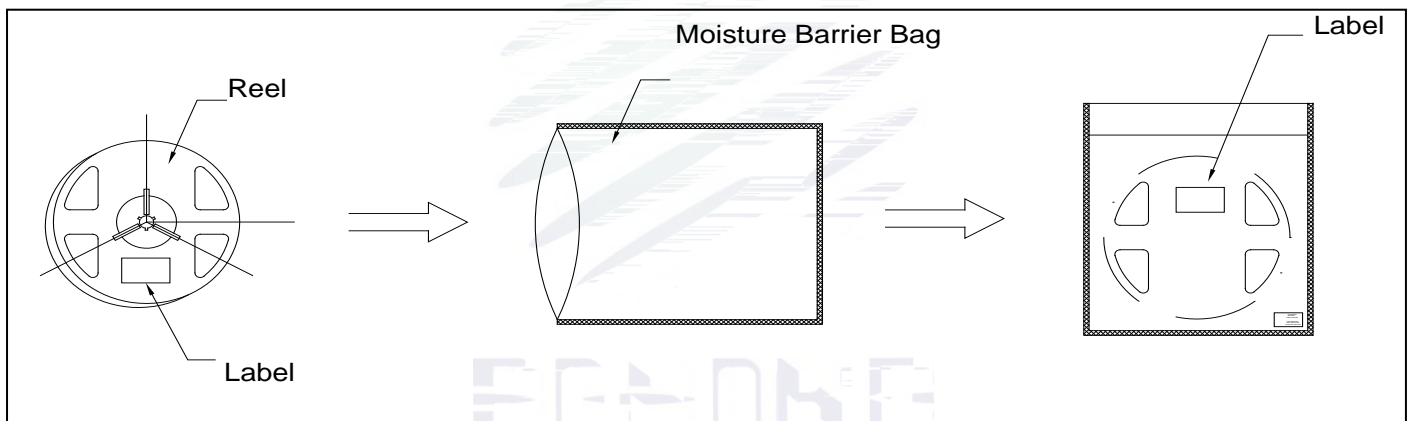


Fig.2-4Moisture Resistant Packing

2.3 Cardboard Box

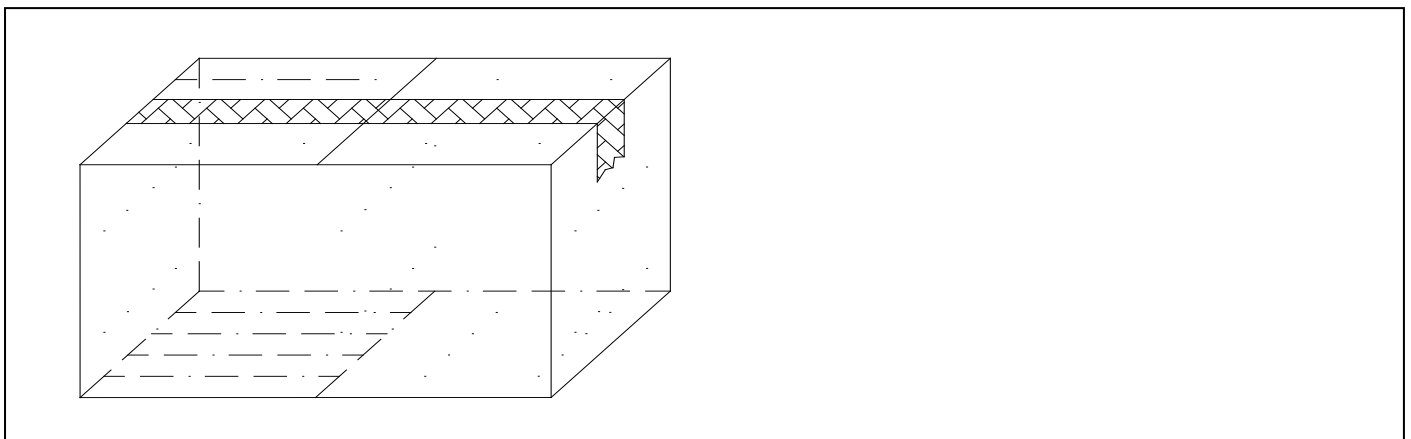


Fig.2-5Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
MSL2 2	JESD22-A113	85 / 60%RH	168 hrs.	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min ↑↓10s 125 15min	1000 cycle	20pcs.	0/1
Life Test	JESD22-A108	Ta=125 If=350mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%RH If=350mA	1000hrs.	20pcs.	0/1



3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

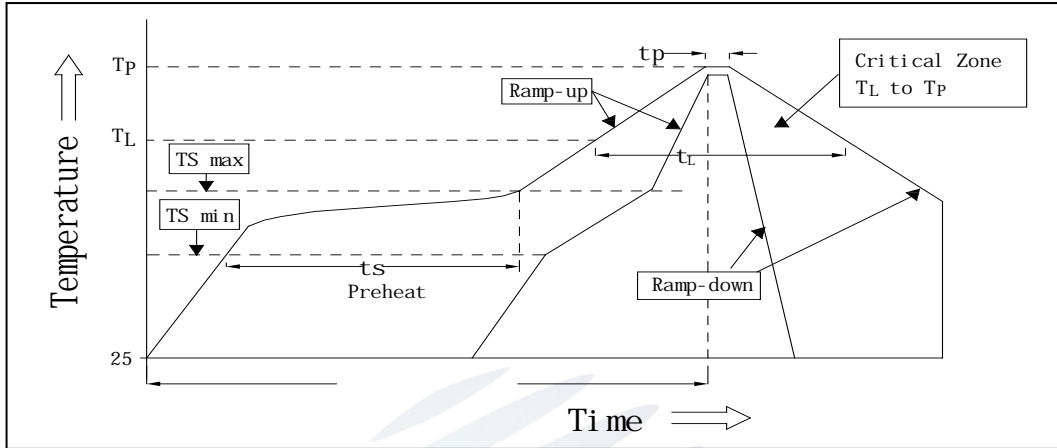


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Reflow parameters

Average temperature rise speed	T_{smax} T_P	3 °C/ Max 3 °C/ s
Preheating: minimum temperature	(T_{smin})	150 °C
Preheating: Max temperature	(T_{smax})	200 °C
Preheating: Time	T_{smin} T_{smax}	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature (T_L)		217 °C
Time limited to maintain high temperature: The Time (t_L)		60 Max 60s
Peak /Classification of temperature:	/ (T_P)	260 °C
Time limit classification of peak temperature time t_p		10 Max 10s
(T_P) 5 °C	Hold time within	30 Max 30s
5 °C with the actual peak temperature (T_P)		
Cooling speed		6 °C/ Max 6 °C/ s
25 °C	Needed time from 25 °C to T_P	8 Max 8 minutes

Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings ,LED will be damaged.

LED

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED

LED

3.1.2 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED

LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.



4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED

LED

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. LED LED

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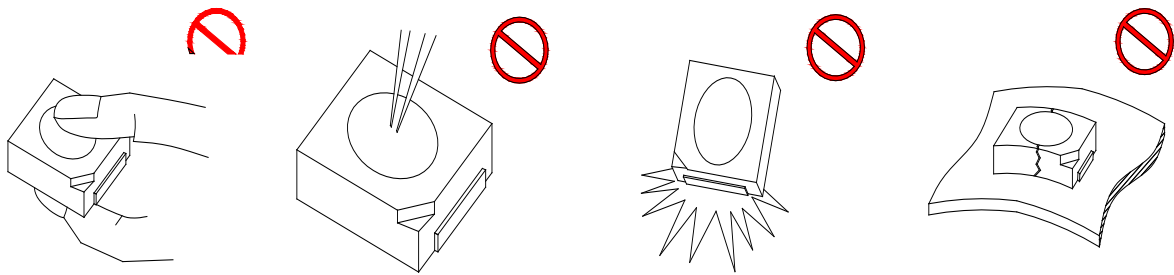


Fig 4-1Cautions

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, other wise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design.

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED

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Declare